2026 IEEE 18th International Conference on Solid-State and Integrated Circuit Technology (ICSICT)

Oct. 27 - 30, 2026 Hangzhou, China

ABOUT CONFERENCE

2026 IEEE 18th International Conference on Solid-State and Integrated Circuit Technology (ICSICT) in the series aiming to provide an international forum for the presentation and discussion of recent advances in solid-state and integrated circuit technology. The conference will be held on Oct. 27 - 30, 2026 in Hangzhou, China.

All aspects of solid-state digital IC & system level design, analog, devices, process technologies and other related research are within the scope of the conference. The ICSICT 2026 Organizing Committee invites you to submit your papers and looks forward to seeing you in Hangzhou!

Track 12: Packaging Technologies

Track Chairs

Jun Zhang

Chair

Nanjing University of Posts and Telecommunications, China

Shenyang Mo

Co-chair

NARI Semiconductor R&D Center, China

Pengfei Zhao

Co-chair

Nanjing University of Posts and Telecommunications, China

Topics

- 2.5D & 3D Integration
- Heterogeneous Integration Packaging
- Advanced Wire Bonding Technology
- Modeling and Simulation for Advanced Packaging
- Testing and Reliability in Advanced Packaging

Publication

Submissions to ICSICT 2026 will be peer reviewed on the basis of technical quality, relevance to conference topics, originality, significance, clarity, etc.

Accepted papers will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements. The proceedings will be submitted for indexing by EI Compendex and Scopus.

Paper Submission

Authors are recommended to submit a 3-page paper; the minimum length is 3 pages and the maximum is 10 double-column pages (including references, tables, and figures).

* View the full submission guidelines:

https://www.icsict.org/Submission.html

* Submit your paper through the following link or QR code:

https://easychair.org/conferences/?conf=icsict2026

Important Dates

Full-Length Paper Submission Deadline	**July 16, 2026**
Notification of Acceptance	August 16, 2026

Co-sponsored by IEEE China Council 中国联合会 · IEEE Beijing Section · 浙江大学 ZHEJIANG UNIVERSITY · 电子科技大学 University of Electronic Science and Technology of China · 武汉理工大学 WUHAN UNIVERSITY OF TECHNOLOGY · 四川省電子學會 Sichuan Institute of Electronics

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